

SEMICONDUCTOR PROCESS POLISHING COMPOSITION, POLISHING
COMPOSITION PREPARATION METHOD, AND SEMICONDUCTOR DEVICE
MANUFACTURING METHOD IN WHICH POLISHING COMPOSITION IS
APPLIED

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ABSTRACT

The present invention relates to a semiconductor process polishing composition and a semiconductor device manufacturing method in which the polishing composition is applied, and can provide a preparation method applied to a CMP process for an amorphous
10 carbon layer, and thus exhibits a high polishing rate, prevents, during a CMP process, the re-adsorption of carbon residue on a semiconductor substrate and the contamination of a polishing pad, and stabilizes an accelerator in the polishing composition so that the storage stability thereof is excellent. In addition, provided is a semiconductor device manufacturing method in which the semiconductor process polishing composition is
15 applied.